



Click [here](#) for the 3D model.

General Information

| | |
|--------------------------|---|
| Series | KONNEKT Comm COG |
| Style | KONNEKT |
| Description | SMD, MLCC, KONNEKT, Ultra-Stable, Class I |
| Features | High Density Packaging |
| RoHS | Yes |
| Termination | Tin |
| AEC-Q200 | No |
| Typical Component Weight | 77.62 mg |
| Chip Size | 1206-2 |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

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|--|---------------------|
| Capacitance | 0.03 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 10% |
| Voltage DC | 500 VDC |
| Dielectric Withstanding Voltage | 750 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 PPM/C |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 33.333 GOhms |

Dimensions

| | |
|---|-----------------|
| L | 3.2mm +/-0.2mm |
| W | 1.6mm +/-0.2mm |
| T | 3.2mm +/-0.4mm |
| B | 0.5mm +/-0.25mm |

Packaging Specifications

| | |
|--------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 500 |

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